



# Manufacturing with Intel® Pentium® 4 Processor in the $\mu$ PGA Form Factor

With Reference Design  
Part IV



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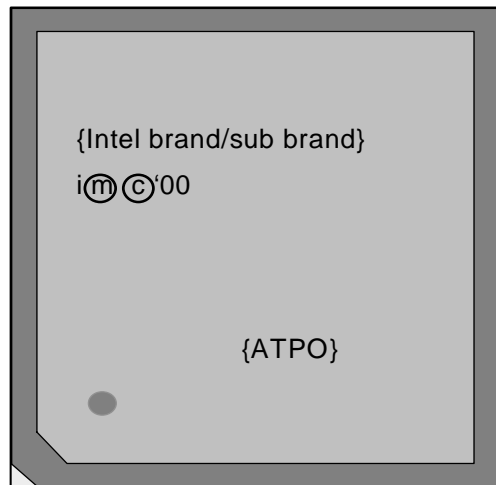
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# Session Agenda

- Mechanical Features
- Reference Design
- Manufacturing Considerations
- **Production Logistics**

# PGA AS A GOLDEN UNIT



- Some users have expressed a desire to use the Intel® Pentium® 4 Processor in the  $\mu$ PGA form factor as a golden unit for verifying the functionality of boards and/or systems.
- Intel specs the number of insertions for the  $\mu$ PGA at 15X.
- See backup information for information.

## Production Logistics: Shipping Media

- Standard JEDEC thick low temperature tray, blue in color, 60C max.
  - Number of units per tray = 24 (3x8 array)
  - Number of trays per stack = 7
  - Number of stacks per box = 2
  - An empty JEDEC tray acts as a cover
- Environmentally friendly pack being 100% recyclable

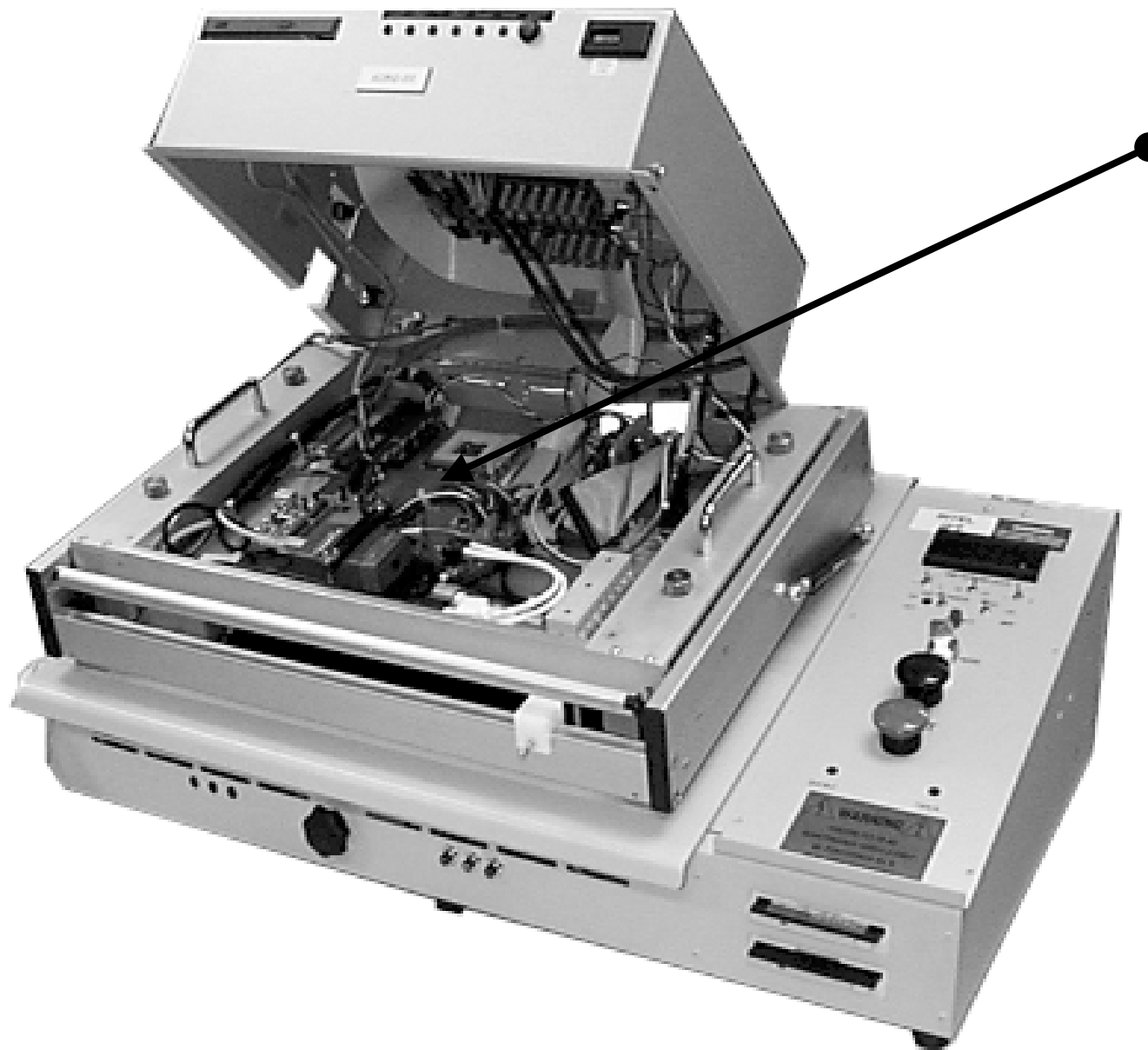


MA

**Backup**

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Top contains  
Gold Hardware

Photo shows  
the top cover  
open.  
CPU, Memory  
and most add-  
in cards are  
accessible from  
this side. This  
cover is  
normally closed  
during TEST  
operation.

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Stabbing  
Solutions

Board  
Under  
Test

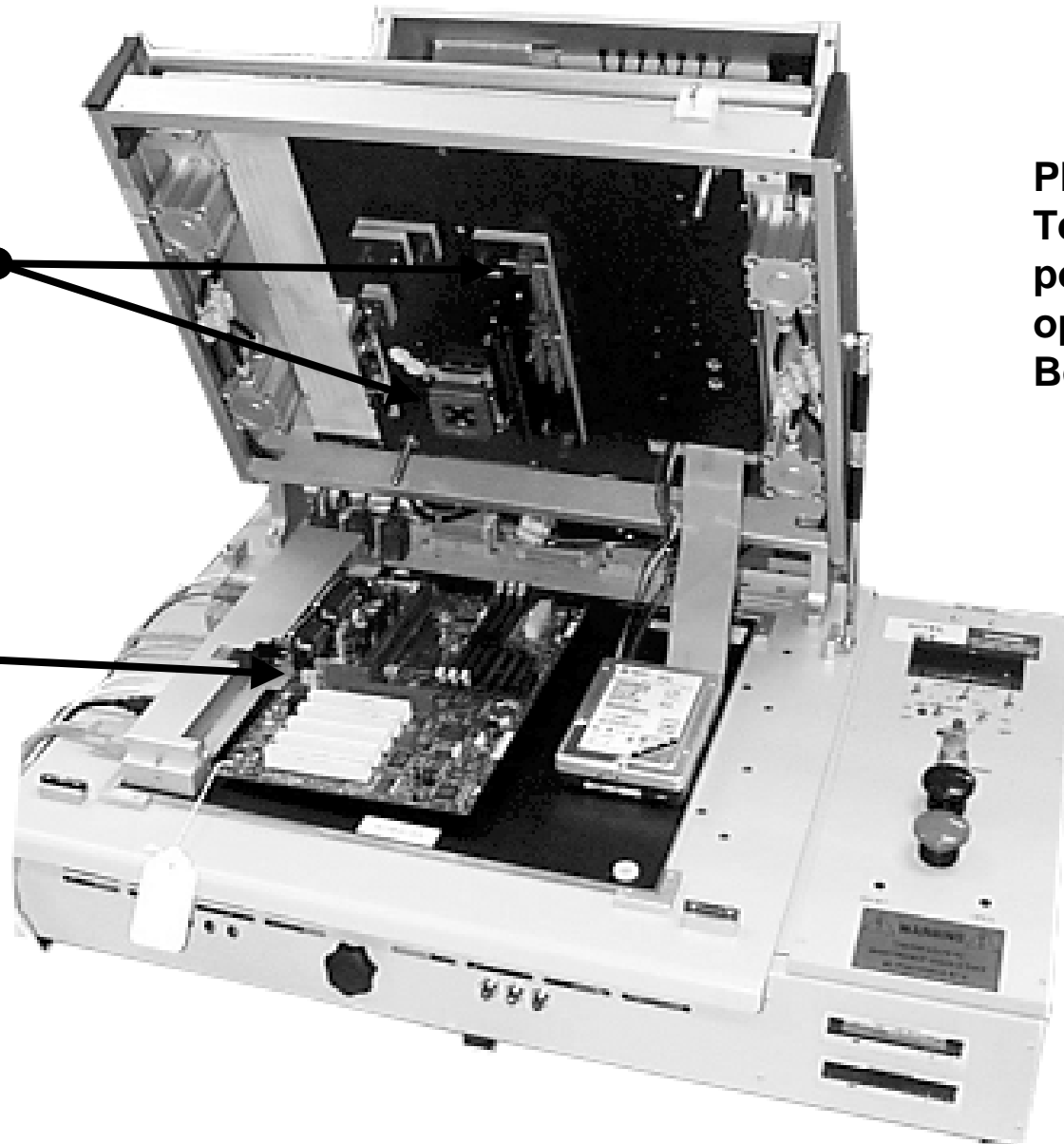


Photo shows the  
Tester in the Open  
position allowing the  
operator to install the  
Board under test